

CLAIMS

~~What is claimed is:~~

1. A system comprising:
 - a particle beam generator in a semiconductor review tool that generates a particle beam;
 - a platen in the semiconductor review tool configured to hold a semiconductor wafer;
 - a detector in the semiconductor review tool configured to receive the particle beam reflected off the semiconductor wafer; and
 - a processor in electronic communication with the detector, wherein the processor is configured to:
 - receive absolute Z-height values with respect to a tool component of the semiconductor review tool, azimuthal angle values, and polar angle values for the semiconductor wafer; and
 - send instructions to review the semiconductor wafer with the particle beam within a Z-height based on the absolute Z-height values at locations of the azimuthal angle values and the polar angle values; and
 - adjust focus of the semiconductor review tool to within the Z-height during the review of the semiconductor wafer.
2. The system of claim 1, wherein the semiconductor wafer has a beveled edge.
- ~~3. The system of claim 1, wherein the processor receives azimuthal angle values and polar angle values with the absolute Z-height values.~~
- ~~43.~~ 43. The system of claim 1, wherein the particle beam is a photon beam.
- ~~54.~~ 54. The system of claim 1, wherein the particle beam is an electron beam.
- ~~6. The system of claim 1, wherein the processor is further configured to adjust focus to within the Z-height.~~
- ~~75.~~ 75. The system of claim 1, wherein the processor is further configured to determine a correlation of the Z-height to a Z-height value of a semiconductor inspection tool separate from the system.

86. The system of claim 75, wherein the correlation is determined at locations at the azimuthal angle values and the polar angle values.

97. A method comprising:

receiving, at a semiconductor review tool, absolute Z-height values with respect to a tool component of the semiconductor review tool, azimuthal angle values, and polar angle values for a semiconductor wafer;

reviewing the semiconductor wafer using the semiconductor review tool at locations of the azimuthal angle values and the polar angle values, wherein the review begins at the absolute Z-height values includes sweeping the Z-height on the semiconductor wafer, and adjusting focus of the semiconductor review tool to within the Z-height during the review of the semiconductor wafer.

108. The method of claim 97, wherein the semiconductor wafer has a beveled edge.

~~11. The method of claim 9, wherein the semiconductor review tool receives azimuthal angle values and polar angle values with the absolute Z-height values.~~

129. The method of claim 97, further comprising:

inspecting a semiconductor wafer with a semiconductor inspection tool; and
determining, using measurements from the semiconductor inspection tool, the absolute Z-height values.

1310. The method of claim 129, further comprising determining a correlation between a second Z-height value from at the second semiconductor inspection tool and the Z-height using the semiconductor inspection tool.

1411. The method of claim 1310, wherein the semiconductor review tool receives azimuthal angle values and polar angle values with the absolute Z-height values, and wherein the correlation is performed at locations at the azimuthal angle values and polar angle values.

1512. A non-transitory computer-readable storage medium, comprising one or more programs for executing the following steps on one or more computing devices:

receiving absolute Z-height values with respect to a tool component of a semiconductor review tool, azimuthal angle values, and polar angle values for a semiconductor wafer; and
sending instructions to review the semiconductor wafer with a particle beam within a Z-height based on the absolute Z-height values at locations of the azimuthal angle values and the polar angle value; and
adjusting focus of the semiconductor review tool to within the Z-height during the review of the semiconductor wafer.

~~16. The non-transitory computer-readable storage medium of claim 15, wherein the steps include adjusting focus to within the Z-height.~~

13. The non-transitory computer-readable storage medium of claim 12, wherein the steps include determining a correlation between a second Z-height value from a second semiconductor inspection tool and the Z-height using the semiconductor inspection tool.

14. The non-transitory computer-readable storage medium of claim 13, wherein the correlation is performed at locations at the azimuthal angle values and the polar angle values.